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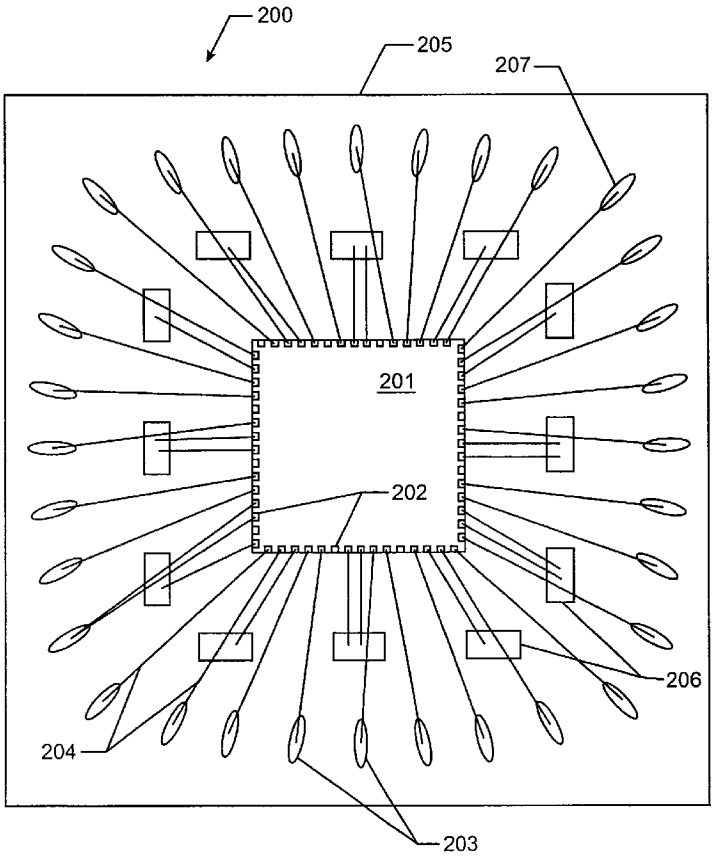
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(54) Title: METHOD FOR ACCOMMODATING SMALL MINIMUM DIE IN WIRE BONDED AREA ARRAY PACKAGES



(57) Abstract: An area array package comprising a die attach area for attaching a die to a substrate, a network of staggered bond fingers, and a network of bond islands for coupling bond wires between the bond islands and die bond pads is provided. A network of package leads, for example, a network of solder balls in a ball grid array, is depopulated to permit greater trace route flexibility and via placement within the substrate. Stacked die and multi-chip packages are also disclosed. A method for accommodating a high pin-count die in an area array package is also included

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